

# (12) International Application Status Report

**Received at International Bureau:** 05 September 2018 (05.09.2018)

**Information valid as of:** 19 November 2018 (19.11.2018)

**Report generated on:** 23 August 2019 (23.08.2019)

**(10) Publication number:**

WO2019/064998

**(43) Publication date:**

04 April 2019 (04.04.2019)

**(26) Publication language:**

Japanese (JA)

**(21) Application Number:**

PCT/JP2018/030833

**(22) Filing Date:**

21 August 2018 (21.08.2018)

**(25) Filing language:**

Japanese (JA)

**(31) Priority number(s):**

2017-190418 (JP)

**(31) Priority date(s):**

29 September 2017 (29.09.2017)

**(31) Priority status:**

Priority document received (in compliance with PCT Rule 17.1)

**(51) International Patent Classification:**

**H05K 1/05** (2006.01); **F04B 39/00** (2006.01); **H05K 1/02** (2006.01); **H05K 1/14** (2006.01); **H05K 3/44** (2006.01); **F16B 5/10** (2006.01)

**(71) Applicant(s):**

IHI CORPORATION [JP/JP]; 1-1, Toyosu 3-chome, Koto-ku, Tokyo 1358710 (JP) *(for all designated states)*

**(72) Inventor(s):**

SASAKI Yuji; c/o IHI Corporation, 1-1, Toyosu 3-chome, Koto-ku, Tokyo 1358710 (JP)

ISHIKAWA Yu; c/o TSS Corporation, 8-20-25, Seishin, Chuoh-ku, Sagamihara-shi, Kanagawa 2520216 (JP)

MATSUZAWA Yoshinobu; c/o TSS Corporation, 8-20-25, Seishin, Chuoh-ku, Sagamihara-shi, Kanagawa 2520216 (JP)

SHISHIDO Masaaki; c/o UNICA CO., LTD, 2-5-13, Imazumidai, Hadano-shi, Kanagawa 2570018 (JP)

**(74) Agent(s):**

HASEGAWA Yoshiki; SOEI PATENT AND LAW FIRM, Marunouchi MY PLAZA (Meiji Yasuda Life Bldg.) 9th fl., 1-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo 1000005 (JP)

**(54) Title (EN):** CIRCUIT BOARD, STRUCTURE FOR CONNECTING CONDUCTIVE MEMBERS, AND ELECTRICALLY-OPERATED COMPRESSOR

**(54) Title (FR):** CARTE DE CIRCUIT IMPRIMÉ, STRUCTURE PERMETTANT DE CONNECTER DES ÉLÉMENTS CONDUCTEURS, ET COMPRESSEUR ACTIONNÉ ÉLECTRIQUEMENT

**(54) Title (JA):** 回路基板、導電部材の接続構造及び電動コンプレッサ

**(57) Abstract:**

**(EN):** This circuit board comprises: a peripheral portion on which an electrical circuit is formed on the surface thereof; an isolating portion on which a terminal is fixed; an insulating portion made from resin, which connects the isolating portion to the peripheral portion; and a reinforcing layer which is provided to the rear surface of the peripheral portion, the rear surface of the isolating portion, and the rear surface of the insulating portion. The reinforcing layer has a portion which covers a first boundary at which the insulating portion comes into contact with the peripheral portion, and a portion which covers a second boundary at which the insulating portion comes into contact with the isolating portion.

**(FR):** La présente invention concerne une carte de circuit imprimé qui comprend : une partie périphérique sur la surface de laquelle est formé un circuit électrique ; une partie d'isolation sur laquelle est fixée une borne ; une partie isolante en résine, qui relie la partie d'isolation à la partie périphérique ; et une couche de renforcement qui est disposée sur la surface arrière de la partie périphérique, la surface arrière de la partie d'isolation et la surface arrière de la partie isolante. La couche de renforcement a une partie qui recouvre une première limite au niveau de laquelle la partie isolante entre en contact avec la partie périphérique, et une partie qui recouvre une seconde limite au niveau de laquelle la partie isolante entre en contact avec la partie d'isolation.

**(JA):** 基板は、表面に電気回路が形成された周辺部と、端子が固定される隔離部と、隔離部を周辺部に連結する樹脂製の絶縁部と、周辺部の裏面、隔離部の裏面及び絶縁部の裏面に設けられた補強層と、を備える。補強層は、絶縁部が周辺部に接する第1境界を覆う部分と、絶縁部が隔離部に接する第2境界を覆う部分と、を有する。

**International search report:**

Received at International Bureau: 19 November 2018 (19.11.2018) [JP]

**International Report on Patentability (IPRP) Chapter II of the PCT:**

Not available

**(81) Designated States:**

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW

European Patent Office (EPO) : AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR

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Eurasian Patent Organization (EAPO) : AM, AZ, BY, KG, KZ, RU, TJ, TM